

LISTING OF CLAIMS

This listing of claims will replace all prior versions and listings of claims in the Application.

1. (Withdrawn – Currently Amended) A method for completely or partly covering at least one electronic component with a compound, ~~wherein in a suitable order, the following steps are traversed~~ comprising:

a) placing the at least one electronic ~~compound is placed~~ component on a first mold half;

b) completely or partly covering the electronic ~~compound is completely or partly covered~~ component with the compound;

c) moving a second mold half ~~which is moveable~~ relative to the first mold half ~~is moved in the direction of the first mold half; and~~ characterized in that

[(e))] d) regulating and adjusting the distance between the two mold halves ~~is continuously regulated and, if desired, adjusted during~~ while the two mold halves ~~being are~~ moved towards each other and ~~during~~ while the two mold halves ~~being~~ are held in a position ~~when~~ after having been moved towards each other during [(the)] curing of the compound.

2. (Withdrawn – Currently Amended) [(A)] The method according to claim 1, wherein, in the position ~~when moved towards each other~~, the mold halves are held at a small distance from each other, so that ~~in the position when moved towards each other~~ ~~too~~, a certain position control range is maintained.

3. (Withdrawn – Currently Amended) [(A)] The method according to claim 1 [(or 2)], wherein step b) takes place after the mold halves have been brought into the position ~~when moved towards each other~~.

4. (Withdrawn – Currently Amended) [[A]] The method according to claim 3, wherein the compound is injected into the mold cavity.

5. (Withdrawn – Currently Amended) [[A]] The method according to claim 3, wherein the compound is placed in the mold cavity and during while the mold halves being are moved towards each other is compressed so as to be spread in the mold cavity.

6. (Withdrawn – Currently Amended) [[A]] The method according to claim 1 [[or 2]], wherein step b) takes place before the mold halves have been brought into the position ~~when moved towards each other~~.

7. (Withdrawn – Currently Amended) [[A]] The method according to claim 6, wherein the compound is placed on the electronic component and, together with the component, is placed on the first mold half.

8. (Withdrawn – Currently Amended) [[A]] The method according to claim 7, wherein the placement of the compound is effected by an inkjet technique, so that the compound is placed on [[the]] desired positions on the electronic component.

9. (Withdrawn – Currently Amended) [[A]] The method according to ~~any one of the preceding claims~~ claim 1, wherein a film is placed between the electronic component and at least one mold half.

10. (Withdrawn – Currently Amended) [[A]] The method according to claim 9, wherein the film ~~also serves~~ is configured for supplying and/or discharging the electronic component into or from the mold cavity, respectively.

11. (Currently Amended) An apparatus for completely or partly covering at least one electronic component with a compound ~~carrying out the method according to any one of the preceding claims~~, wherein the apparatus is provided comprising:

_____ ~~[[with]]~~ a first mold half; ~~[[and]]~~

_____ a second mold half, wherein the first mold half is moveable relative to the second mold half ~~[[, while]]~~;

~~means are provided for placing a cavity, being defined by the two mold halves, configured to receive the~~ ~~[[an]]~~ ~~electronic component on a mold half for inclusion of the component in a mold cavity defined by the two mold halves~~ ~~[[,]]~~ ~~characterized in that;~~

~~at least one actuator connected with~~ the first mold half ~~is provided with a number of actuators and configured to regulate with the aid of which~~ the position of the first mold half relative to the second mold half; ~~and is continuously and accurately regulable, the apparatus being provided with~~

a controller ~~for regulating configured to control~~ the positions of ~~said number of actuators~~ ~~the at least one actuator~~, so that the distance between the two mold halves is continuously regulated ~~[[,]]~~ and, ~~if desired,~~ adjusted ~~during while~~ the two mold halves being ~~are~~ moved towards each other and ~~during while~~ the two mold halves being ~~are~~ held in a position ~~when- after having been~~ moved towards each other.

12. (Currently Amended) ~~[[An]]~~ The apparatus according to claim 11, wherein the controller ~~is arranged for holding configured to hold~~ the two mold halves at a small distance from each other in the position ~~when moved towards each other~~, so that ~~in the position when moved towards each other too~~, a certain position control range is maintained.

13. (Currently Amended) ~~[[An]]~~ The apparatus according to claim 11 ~~[[or 12]]~~, wherein further comprising:

_____ a component supply and discharge device ~~is provided, which is arranged configured for placing and removing to place or remove~~ an electronic component on or from said first mold half, respectively.

14. (Currently Amended) ~~[[An]]~~ The apparatus according to ~~any one of claims claim 11~~ [[13]], further comprising:
_____ wherein a film supply and discharge device is provided for supplying configured to supply film to the mold cavity and discharging film from the mold cavity.

15. (Currently Amended) ~~[[An]]~~ The apparatus according to ~~claims claim 13~~ [[and 14]], further comprising:
_____ a film supply and discharge device configured to supply film to the mold cavity and discharging film from the mold cavity wherein the film supply and discharge device also forms the component supply device.

16. (Currently Amended) ~~[[An]]~~ The apparatus according to ~~any one of claims claim 11 —15, provided with further comprising:~~
a compound supply provision.

17. (Currently Amended) ~~[[An]]~~ The apparatus according to claim 16, wherein the compound supply provision is ~~arranged for supplying~~ configured to supply the compound to the mold cavity when the mold halves are in the position when moved towards each other.

18. (Currently Amended) ~~[[An]]~~ The apparatus according to claim 16, wherein the compound supply provision is ~~arranged for placing~~ configured to place the compound on an electronic component which is placed on a mold half.

19. (Currently Amended) ~~[[An]]~~ The apparatus according to claim 16, wherein the compound supply provision is ~~arranged for placing~~ configured to place the compound on an electronic component present outside the mold cavity.

20. (Currently Amended) ~~[[An]]~~ The apparatus according to claim 18 ~~[[or 19]]~~, wherein the compound supply provision comprises an inkjet head and a compound reservoir connected to the inkjet head.

21. (New) The apparatus according to claim 19, wherein the compound supply provision comprises an inkjet head and a compound reservoir connected to the inkjet head.

22. (New) The method according to claim 1, wherein the regulating and adjusting comprises:
continuously regulating and adjusting the distance between the two mold halves.

23. (New) The apparatus according to claim 11, wherein
the controller is configured to continuously regulate the positions of the at least one actuator.